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IN THE CLAIMS

Please substitute the following listing of claims for the previous listing of claims.

- (Currently amended) A substrate processing apparatus comprising:
 a process chamber comprising a substrate support, gas inlet, gas energizer, gas exhaust, and a wall having a radiation permeable wall portion, the radiation permeable wall portion comprising a plurality of recesses recess sized to reduce the deposition of process residues therein.
- 2. (Currently amended) An apparatus according to claim 1 further comprising a process monitoring system capable of monitoring a process that may be conducted in the process chamber through the <u>a</u> recess in the <u>radiation permeable</u> wall portion.
- 3. (Currently amended) An apparatus according to claim 1 wherein the recess originates at an internal surface of the radiation permeable wall portion.
- 4. (Currently amended) An apparatus according to claim 3 wherein the recess terminates at a recesses terminate in the radiation permeable wall portion of the wall.
- 5. (Currently amended) An apparatus according to claim 1 wherein the recess comprises recesses comprise an aspect ratio of at least about 0.25:1.
- 6. (Currently amended) An apparatus according to claim 5 wherein the recess comprises recesses comprise an aspect ratio of at least about 3:1.

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- 7. (Currently amended) An apparatus according to claim 5 wherein the recess comprises recesses comprise an aspect ratio of less than about 12:1.
- 8. (Currently amended) An apparatus according to claim 1 wherein the recess comprises recesses comprise an opening size of from about 0.1 to about 50 mm.
- 9. (Currently amended) An apparatus according to claim 1 wherein the recess-comprises recesses comprise a depth of from about 0.5 to about 500 mm.
- 10. (Currently amended) An apparatus according to claim 1 wherein the recess comprises recesses comprise a diameter of less than about 10 times a thickness of a plasma sheath that may be formed in the chamber.

11. (Canceled)

(Currently amended) An apparatus according to claim 1 wherein the <u>radiation permeable</u> wall <u>portion</u> comprises one or more of Al₂O₃, SiO₂, AlN, BN, Si, SiC, Si₃N₄, TiO₂, ZrO₂ and mixtures and compounds thereof.

(Currently amended) An apparatus according to claim 12 wherein the <u>radiation permeable</u> wall <u>portion</u> comprises quartz.

14. (Canceled)

(Currently amended) An apparatus according to claim 1 wherein the wall turther comprises a masking portion having the recess therein.

16-17. (Withdrawn)

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(Currently amended) A substrate processing apparatus comprising:

- (i) a chamber having a support, gas inlet, gas energizer, and exhaust, and a wall ceiling having an integral radiation permeable wall portion, the radiation permeable wall portion having a recess sized to reduce the deposition of process residues therein; and
- (ii) means for reducing the formation of process residue on the wall,

whereby a substrate held on the support may be processed by process gas introduced by the gas inlet, energized by the gas energizer, and exhausted by the exhaust.

- 19. (Canceled)
- (Currently amended) An apparatus according to claim <u>18</u> 19 wherein the <u>means recess</u> controls an access of energized gas species to the radiation permeable <u>wall</u> portion.
 - 21. (Canceled)
- \(\(\frac{1}{2}\) (Currently amended) An apparatus according to claim \(\frac{16}{24}\) wherein the recesses comprise an aspect ratio of at least about 0.25:1.
- (Currently amended) An apparatus according to claim 18 further comprising a process monitoring system to monitor radiation passing through the radiation permeable wall portion.

24-29. (Withdrawn)

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(Original) A substrate processing apparatus comprising: a process chamber comprising

- a substrate support,
- a gas inlet,
- a gas energizer,
- a gas exhaust, and

a wall comprising <u>a radiation permeable wall portion</u>, the <u>radiation permeable wall portion having a plurality of recesses</u> a recess originating at an internal surface of the <u>radiation permeable</u> wall <u>portion</u>, the <u>recess recesses</u> having an aspect ratio sized to reduce the deposition of process residues therein.

(Currently amended) An apparatus according to claim 30 further comprising a radiation permeable portion in the recess, and a process monitoring system capable of monitoring a process that may be conducted in the chamber through the radiation permeable wall portion.

(Currently amended) An apparatus according to claim 30 wherein the recess comprises recesses comprise an aspect ratio of at least about 0.25:1.

(Currently amended) An apparatus according to claim 30 wherein the recess comprises recesses comprise a passageway inclined at an angle of less than about 90 degrees.

(Currently amended) An apparatus according to claim 3Q wherein the <u>radiation permeable</u> wall <u>portion</u> comprises one or more of Al₂O₃, SiO₂, AlN, BN, Si, SiC, Si₃N₄, TiO₂, ZrO₂ and mixtures and compounds thereof.

35. (Canceled)

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36. (Currently amended) An apparatus according to claim 30 35 wherein the recesses are arranged to pass therethrough radiation originating from the plasma or radiation reflected from different portions of the substrate.

37-50. (Withdrawn)

(Currently amended) A substrate processing apparatus comprising:
a process chamber comprising a substrate support, a gas inlet, a
gas energizer, a gas exhaust, and a sidewall about the support, the sidewall having an
integral radiation permeable wall portion, the radiation permeable wall portion
comprising at least one recess sized to reduce the deposition of process residues
therein.

25 52: (Original) An apparatus according to claim 51 further comprising a second recess in the sidewall.

24 58. (Original) An apparatus according to claim 51 wherein the recess is inclined relative to the sidewall.

(Original) An apparatus according to claim 53 wherein the recess is inclined from about 50 degrees to about 60 degrees relative to the sidewall.

(Currently amended) An apparatus according to claim 51 further comprising a process monitoring system capable of monitoring a process that may be conducted in the process chamber through the recess in the <u>radiation permeable</u> wall <u>portion</u>.

58. (Currently amended) An apparatus according to claim 51 wherein the recess originates at an internal surface of the radiation permeable wall portion sidewall.

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(Currently amended) An apparatus according to claim 56 wherein the recess terminates at a in the radiation permeable wall portion of the sidewall.

(Original) An apparatus according to claim 51 wherein the recess comprises an aspect ratio of at least about 0.25:1.

37 24 59. (Original) An apparatus according to claim-51 wherein the recess comprises an opening size of from about 0.1 to about 50 mm.

(Original) An apparatus according to claim 54 wherein the recess comprises a depth of from about 0.5 to about 500 mm.

(Currently amended) An apparatus according to claim of wherein the sidewall radiation permeable wall portion comprises a plurality of recesses.

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62. (Original) An apparatus according to claim of wherein the sidewall comprises a plurality of recesses on opposing sides of the support.

(Currently amended) An apparatus according to claim of wherein the sidewall further comprises a masking portion having the recess therein.

64. (Original) An apparatus according to claim 54 further comprising an electromagnetic field source adapted to maintain an electromagnetic field about the recess.

65-69. (Withdrawn)